

## 1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

<b>Part Number :</b>	CJAC75SN10
<b>Package Type :</b>	PDFNWB5x6-8L

## 2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total	
Wafer	Silicon	7440-21-3	100.0000%	4.63%	
Lead Frame	Copper	7440-50-8	97.5200%	34.28%	
	Iron	7439-89-6	2.3500%		
	P	7723-14-0	0.0800%		
	Plating Ag	7440-22-4	0.0500%		
Solder	Lead	7439-92-1	85.0000%	3.66%	
	Tin	7440-31-5	4.3500%		
	Silver	7440-22-4	2.1500%		
	Butanediol mixture	107-88-0	7.5000%		
	Modified castor oil	61788-85-0	1.0000%		
Wire	Ribbon	7429-90-5	100.0000%	2.43%	
	AuPdCu	Copper	7440-50-8		97.9500%
		Palladium	7440/5/3		1.8000%
		Gold	7440-57-5		0.2500%
Mold Compound	Silica	60676-86-0	82.0000%	52.59%	
	Epoxy Resin	85954-11-6	10.0000%		
	Phenol Resin	26834-02-6	7.5000%		
	Carbon black	1333-86-4	0.5000%		
Plating	Tin	7440-31-5	99.9900%	2.41%	
	Other	/	0.0100%		

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.